

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	SAK-XC167CI-32F40F BB-A	**Issued**	12. August 2019
MA#	MA001322924		
Package	PG-TQFP-144-7	**Weight***	1403.65 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	33.010	2.35	2.35	23517	23517
leadframe	non noble metal	magnesium	7439-95-4	0.529	0.04		377	
	inorganic material	silicon	7440-21-3	2.293	0.16		1633	
	non noble metal	nickel	7440-02-0	10.581	0.75		7539	
	non noble metal	copper	7440-50-8	339.310	24.17	25.12	241735	251284
wire	noble metal	gold	7440-57-5	3.622	0.26	0.26	2580	2580
encapsulation	organic material	carbon black	1333-86-4	4.974	0.35		3543	
	plastics	epoxy resin	-	134.293	9.57		95674	
	inorganic material	silicondioxide	60676-86-0	855.493	60.95	70.87	609478	708695
leadfinish	non noble metal	tin	7440-31-5	8.638	0.62	0.62	6154	6154
plating	noble metal	silver	7440-22-4	4.833	0.34	0.34	3443	3443
glue	plastics	epoxy resin	-	1.215	0.09		865	
	noble metal	silver	7440-22-4	4.859	0.35	0.44	3462	4327
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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